



CFP2-100GB-ER4-OPC

MSA Complaint 100GBase-ER4 CFP2 Transceiver (SMF, 1310nm, 40km, LC, DOM)

Features

- CFP MSA 1.0 Compliance
- Duplex LC Connector
- Single-mode Fiber
- Commercial Temperature 0 to 70 Celsius
- Hot Pluggable
- Metal with Lower EMI
- Excellent ESD Protection
- RoHS Compliant and Lead Free



Applications:

- 100GBase Ethernet

Product Description

This industry standard CFP2 transceiver provides 100GBase-ER4 throughput up to 40km over single-mode fiber (SMF) using a wavelength of 1310nm via an LC connector. It has been programmed, uniquely serialized, and tested for data-traffic and application to ensure that it will initialize and perform identically. All of our transceivers comply with Multi-Source Agreement (MSA) standards to provide seamless network integration. Additional product features include Digital Optical Monitoring (DOM) support which allows access to real-time operating parameters. We stand behind the quality of our products and proudly offer a limited lifetime warranty.

OptioConnect's transceivers are RoHS compliant and lead-free.

Absolute Maximum Ratings

Parameter	Symbol	Min.	Max.	Unit
Storage Temperature	T _s	-40	85	°C
Supply Voltage	V _{cc}	-0.5	3.6	V
Operating Relative Humidity	RH	0	85	%

Note:

1. Exceeding any one of these values may destroy the device immediately.

Recommended Operating Conditions

Parameter	Symbol	Min.	Typ.	Max.	Unit
Operating Case Temperature	TC	0		70	°C
Power Supply Voltage	V _{cc}	3.14	3.3	3.46	V
Data Rate	DR		103.2	112	Gb/s

Electrical Characteristics

Parameter			Symbol	Min.	Typ.	Max.	Unit	Notes
Voltage Supply Electrical Characteristics								
Supply Current		Tx Section	Icc	A			3.75	1
		Rx Section						
Power Supply Noise			Vrip				2% DC	1MHz
							3% 1	10MHz
Total Dissipation Power		Class1	Pw	W			3	
		Class2					6	
		Class3					9	
		Class4					12	
Low Power Mode Dissipation			Plow	W			2	
Inrush Current	Class1	and	I-inrush	mA/usec			100	
Turn-off Current	Class2		I-turnoff	mA/usec	-100			
Inrush Current	Class3	and	I-inrush	mA/usec			200	
Turn-off Current	Class4		I-turnoff	mA/usec	-200			
Different Signal Electrical Characteristics								
Single Ended Data Input Swing				mV	20		525	
Single Ended Data Output Swing				mV	180		385	
Differential Signal Output Resistance				Ω	80		120	
Differential Signal Input Resistance				Ω	80		120	
3.3V LVCMOS Electrical Characteristics								
Input High Voltage			3.3VIH	V	2.0		Vcc+0.3	
Input Low Voltage			3.3VIL	V	-0.3		0.8	
Input Leakage Current			3.3IIN	uA	-10		+10	
Output High Voltage (IOH=100uA)			3.3VOH	V	Vcc-0.2			
Output Low Voltage (IOL=100uA)			3.3VOL	V			0.2	
Minimum Pulse Width of Control Pin Signal			t_CNTL	us	100			
1.2V LVCMOS Electrical Characteristics								
Input High Voltage			1.2VIH	V	0.84		1.5	
Input Low Voltage			1.2VIL V	0.3	1.2VIL V		0.36	
Input Leakage Current			1.2IIN	uA	-100		+100	
Output High Voltage			1.2VOH	V	1.0		1.5	
Output Low Voltage			1.2VOL	V	-0.3		0.2	
Output High Current			1.2IOH	mA			-4	
Output Low Current			1.2IOL	mA	+4			
Input Capacitance			Ci	pF			10	

High Speed Electrical Characteristics

Parameter	Symbol	Unit	Min.	Max.	Notes
Impedance	Zd	Ω	90	110	
Frequency		MHz	161.1328125		1/64 of electrical lane rate
Frequency Stability	Δf	ppm	-100	100	For Ethernet
			-20	20	For Telecom
Differential Voltage	VDIFF	mV	400	900	Peak to Peak Differential
Common mode noise (rms)		mV		17.5	
RMS jitter		ps		10	Random Jitter Over frequency band of 10KHZ<f<10MHZ
Clock Duty Cycle		%	40	60	

Optical Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Notes
Transmitter						
Signaling Rate per Lane		25.78125 ±100 ppm			GBd	9
		27.9525 ±20 ppm			GBd	OTU4
Four Lane Wavelength Range	λ1	1294.53	1295.56	1296.59	nm	
	λ2	1299.02	1300.05	1301.09	nm	
	λ3	1303.54	1304.58	1305.63	nm	
	λ4	1308.09	1309.14	1310.19	nm	
Total launch power				8.9	dBm	9
Average launch power, each lane	Pavg	-2.9		2.9	dBm	2
Optical modulation amplitude, each lane (OMA) ²	OMA	0.1		4.5	dBm	
Difference in launch power between any two lanes (OMA)				3.6	dB	
Extinction ratio	ER	8			dB	9
Side-mode suppression ratio	SMSR	30			dB	
Transmitter and dispersion penalty, each lane	TDP			2.5	dB	
Optical return loss tolerance				20	dB	
Transmitter reflectance ³				−12	dB	
Transmitter eye mask {X1, X2, X3, Y1, Y2, Y3}		{0.25, 0.4, 0.45, 0.25, 0.28, 0.4}				9
Receiver						
Receive Rate for Each Lane			25.78125	27.9525	Gbps	
Overload Input Optical Power	Pmax	5.5			dBm	3
Average Receive Power for Each Lane	Pin	-16		4.5	dBm	4, 5 (-

						20.9)
Receive Power in OMA for Each Lane	PinOMA			4.5	dBm	
Difference in Receive Power in OMA between Any Two Lanes				4.5	dBm	
Receiver Sensitivity in OMA for Each Lane	SOMA			-16	dBm	6 (-21.4)
Stressed Receiver Sensitivity in OMA for Each Lane				-12	dBm	7, 8 (-17.9)

Notes:

1. The supply current includes CFP2 module's supply current and test board working current.
2. Average launch power, each lane (min) is informative for 100GBase-LR4, not the principal indicator of signal strength.
3. The receiver shall be able to tolerate, without damage, continuous exposure to an optical input signal having this average power level
4. The average receive power, each lane (max) for 100GBASE-ER4 is larger than the 100BASE-ER4 transmitter value to allow compatibility with 100BASE-LR4 units at short distances
5. Average receive power, each lane (min) is informative and not the principal indicator of signal strength. A received power below this value cannot be compliant; however, a value above this does not ensure compliance
6. Receiver sensitivity (OMA), each lane (max) is informative
7. Measured with conformance test signal at TP3 for BER=10⁻¹²
8. Conditions of stressed receiver sensitivity test: vertical eye closure penalty for each lane is 1.8dB; stressed eye J2 jitter for each lane is 0.3UI; stressed eye J9 jitter for each lane is 0.47UI.
9. 100GBase-ER4

Pin Descriptions

Pin	Name	I/O	Logic	Description
1	GND			
2	(TX_MCLKn)	O	CML	For optical waveform testing. Not for normal use.
3	(TX_MCLKp)	O	CML	For optical waveform testing. Not for normal use.
4	GND			
5	N.C			No Connect
6	N.C			3.3V $\pm$ 5%
7	3.3V_GND			3.3V Module Supply Voltage Return Ground, can be separate or tied together with Signal Ground
8	3.3V_GND			3.3V Module Supply Ground, internally connected to Signal Ground
9	3.3V			3.3V Module Supply Voltage
10	3.3V			Module Vendor I/O B, NC
11	3.3V			"1" or NC = transmitter disabled, "0" = transmitter enabled
12	3.3V			"1" = loss of signal (low optical signal), "0" = normal condition
13	3.3V_GND			3.3V Module Supply Voltage Return Ground, can be separate or tied together with Signal Ground
14	3.3V_GND			"1" or NC = module in low power (safe) mode, "0" = power-on enabled
15	VND_IO_A	I/O		Module Vendor I/O A. Do Not Connect!
16	VND_IO_B	I/O		Module Vendor I/O A. Do Not Connect!
17	PRG_CNTL1	I	LVC MOS w/ PUR	Programmable Control 1 set over MDIO, MSA Default: TRXIC_RSTn, TX & RX ICs reset, "0": reset, "1" or NC: enabled = not used
18	PRG_CNTL2	I	LVC MOS w/ PUR	Programmable Control 2 set over MDIO, MSA Default: Hardware Interlock LSB, "00": $\leq$ 3W, "01": $\leq$ 6W, "10": $\leq$ 9W, "11" or NC: $\leq$ 12W = not used
19	PRG_CNTL3	I	LVC MOS w/ PUR	Programmable Control 2 set over MDIO, MSA Default: Hardware Interlock LSB, "00": $\leq$ 3W, "01": $\leq$ 6W, "10": $\leq$ 9W, "11" or NC: $\leq$ 12W = not used
20	PRG_ALRM1	O	LVC MOS	Programmable Alarm 1 set over MDIO, MSA Default: HIPWR_ON, "1": module power up completed, "0": module not high powered up
21	PRG_ALRM2	O	LVC MOS	Programmable Alarm 2 set over MDIO, MSA Default: MOD_READY, "1": Ready, "0": not Ready.
22	PRG_ALRM3	O	LVC MOS	Programmable Alarm 3 set over MDIO, MSA Default: MOD_FAULT, fault detected, "1": Fault, "0": No Fault
23	GND			
24	TX_DIS	I	LVC MOS w/ PUR	Transmitter Disable for all lanes, "1" or NC = transmitter disabled, "0" = transmitter enabled
25	RX_LOS	O	LVC MOS	Receiver Loss of Optical Signal, "1": low optical signal, "0": normal condition
26	MOD_LOPWR	I	LVC MOS w/ PUR	Module Low Power Mode. "1" or NC: module in low power (safe) mode, "0": power-on enabled
27	MOD_ABS	O	GND	Module Absent. "1" or NC: module absent, "0": module present, Pull Up Resistor on Host
28	MOD_RSTn	I	LVC MOS w/ PDR	Module Reset. "0" resets the module, "1" or NC = module enabled, Pull Down Resistor in Module
29	GLB_ALRMn	O	LVC MOS	Global Alarm. "0": alarm condition in any MDIO Alarm register, "1": no alarm condition, Open Drain, Pull Up Resistor on Host
30	GND			

31	MDC	I	1.2VCMOS	Management Data Clock (electrical specs as per IEEE Std 802.3ae-2008 and ba-2010)
32	MDIO	I/O	1.2VCMOS	Management Data I/O bi-directional data (electrical specs as per IEEE Std 802.3ae-2008 and ba-2010)
33	PRTADR0	I	1.2VCMOS	MDIO Physical Port address bit 0
34	PRTADR1	I	1.2VCMOS	MDIO Physical Port address bit 1
35	PRTADR2	I	1.2VCMOS	MDIO Physical Port address bit 2
36	VND_IO_C	I/O		Module Vendor I/O C. Do Not Connect!
37	VND_IO_D	I/O		Module Vendor I/O D. Do Not Connect!
38	VND_IO_E	I/O		Module Vendor I/O E. Do Not Connect!
39	3.3V_GND			
40	3.3V_GND			
41	3.3V			3.3V Module Supply Voltage
42	3.3V			3.3V Module Supply Voltage
43	3.3V			3.3V Module Supply Voltage
44	3.3V			3.3V Module Supply Voltage
45	3.3V_GND			
46	3.3V_GND			
47	N.C			No Connect
48	N.C			
49	GND			
50	(RX_MCLKn)	O	CML	For optical waveform testing. Not for normal use.
51	(RX_MCLKp)	O	CML	For optical waveform testing. Not for normal use.
52	GND			
53	GND			
54	N.C.			
55	N.C.			
56	GND			
57	RX0p			25 Gbps receiver data; Lane 0
58	RX0n			25 Gbps receiver data bar; Lane 0
59	GND			
60	RX1p			25 Gbps receiver data; Lane 1
61	RX1n			25 Gbps receiver data bar; Lane 1
62	GND			
63	N.C.			
64	N.C.			
65	GND			
66	N.C.			
67	N.C.			
68	GND			
69	RX2p			25 Gbps receiver data; Lane 2
70	RX2n			25 Gbps receiver data bar; Lane 2
71	GND			
72	RX3p			25 Gbps receiver data; Lane 3

73	RX3n			25 Gbps receiver data bar; Lane 3
74	GND			
75	N.C.			
76	N.C.			
77	GND			
78	(REFCLKp)		CML	Module reference clock. No connect.
79	(REFCLKn)		CML	Module reference clock. No connect.
80	GND			
81	N.C.			
82	N.C.			
83	GND			
84	TX0p			25 Gbps transmitter data; Lane 0
85	TX0n			25 Gbps transmitter data bar; Lane 0
86	GND			
87	TX1p			25 Gbps transmitter data; Lane 1
88	TX1n			25 Gbps transmitter data bar; Lane 1
89	GND			
90	N.C.			
91	N.C.			
92	GND			
93	N.C.			
94	N.C.			
95	GND			
96	TX2p			25 Gbps transmitter data; Lane 2
97	TX2n			25 Gbps transmitter data bar; Lane 2
98	GND			
99	TX3p			25 Gbps transmitter data; Lane 3
100	TX3n			25 Gbps transmitter data bar; Lane 3
101	GND			
102	N.C.			
103	N.C.			
104	GND			

Hardware Control Pins

The CFP2 Module support real-time control functions via hardware pins, listed in the following.

Pin	Symbol	Description	I/O	Logic	H	L	Pull-up/down
17	PRG_CNTL1	Programmable Control 1 MSA Default: TRXIC_RS Tn, TX&RX ICs reset, "0": reset;"1"	I	3.3V LVCMOS	per CFP MSA Management Interface Specification		Pull-Up Note1
18	PRG_CNTL2	Programmable Control 2 MSA Default: Hardware Interlock LSB	I	3.3V LVCMOS			Pull-Up Note1
19	PRG_CNTL3	Programmable Control 3 MSA Default: Hardware Interlock MSB	I	3.3V LVCMOS			Pull-Up Note1
26	MOD_LOPW R	Module Low Power Mode	I	3.3V LVCMOS Low Power Enable Pull-Up	Low Power	Enable	Pull-Up Note1
28	MOD_RSTn	Module Reset (Invert)	I	3.3V LVCMOS	Enable	Reset	Pull-Down Note2

Notes:

1. Pull-Up resistor (4.7KOhm to 10 KOhm) is located within the CFP2 module
2. Pull-Down resistor (4.7KOhm to 10 kOhm) is located within the CFP2 module

Hardware Alarm Pins

The CFP2 Module supports alarm hardware pins listed in the following

Pin	Symbol	Description	I/O	Logic	H	L	Pull-up/down
20	PRG_ALR M1	Programmable Alarm 1 MSA Default: HIPWR_ON	O	3.3V LVCMOS	Active High per MDIO document		
21	PRG_ALR M2	Programmable Alarm 2 MSA default: MOD_READY, Ready State has been reached	O	3.3V LVCMOS			
22	PRG_ALR M3	Programmable Alarm 3 MSA Default: MOD_FAULT	O	3.3V LVCMOS			
27	MOD_ABS	Module Absent	O	3.3V LVCMOS	Absent	Present	Pull-Down Note1
25	RX_LOS	Receiver Loss of Signa	O	3.3V LVCMOS	Loss of Signal	OK	

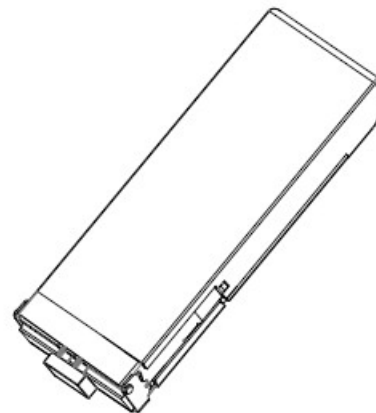
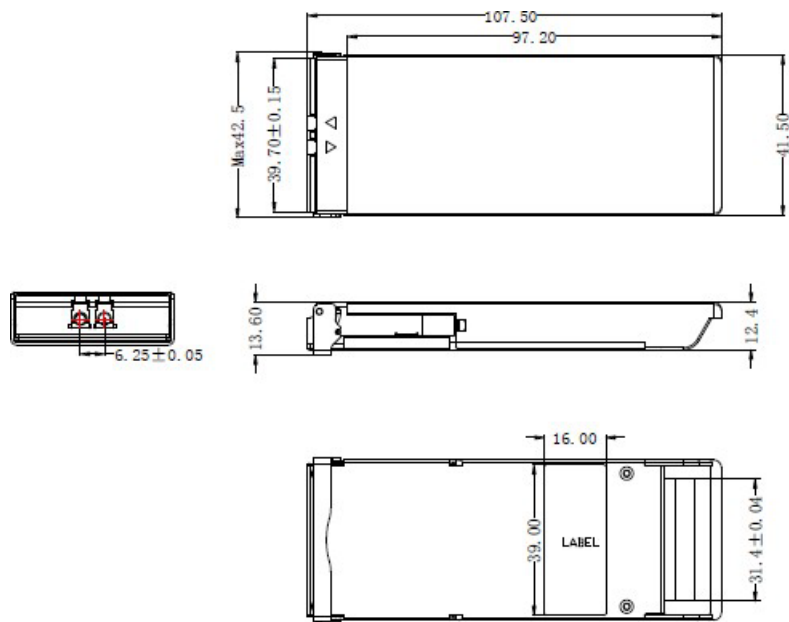
Note:

1. Pull-Down resistor (<100Ohm) is located within the CFP2 module. Pull-up should be located on the host

CFP2 Lane Assignment

Lane	Center Frequency	Center Wavelength	Wavelength Range
L0	231.4 THz	1295.56 nm	1294.53 to 1296.59 nm
L1	230.6 THz	1300.05 nm	1299.02 to 1301.09 nm
L2	229.8 THz	1304.58 nm	1303.54 to 1305.63 nm
L3	229.0 THz	1309.14 nm	1308.09 to 1310.19 nm

Mechanical Specifications



Units in mm
Tolerance without indication is $\pm 0.2\text{mm}$

OptioConnect

Innovation for the Future of High-Speed Networking

Who We Are

OptioConnect is reshaping the landscape of communication and high-speed networking through intelligent technology. With a core focus on cutting edge technology, we deliver smarter fiber optic solutions for enterprise networks, data centers, and next-gen telecom infrastructures.

What We Do

At OptioConnect, we fuse advanced engineering with intelligent automation to drive the future of networking. Our AI-integrated solutions are designed to optimize performance and streamline operations with:

- Superior Performance
- Network and traffic optimization
- Intelligent energy management
- Seamless OEM compatibility
- Scalable cost-efficiency

Smarter Networks by Design

Innovation isn't just a goal—it's our process. We embed AI and machine learning across our R&D and product lines, enabling adaptive performance, automated tuning, and faster deployment cycles. The result? Networks that don't just work—they learn, evolve, and outperform.

Our Team

Our engineers, data scientists, and network architects bring decades of experience and a future-focused mindset. We provide hands-on support with intelligent insights that turn complex challenges into simple solutions.

Our Mission

To deliver AI-enhanced connectivity that reduces cost, increases speed, and maximizes efficiency—empowering our partners to operate at the forefront of a rapidly evolving digital world.

Let's Connect

Discover how OptioConnect's intelligent infrastructure solutions can power your network's next leap forward.

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